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JOINT INDUSTRY STANDARD

Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices

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The material in this joint standard was developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the IPC Plastic Chip Carrier Cracking Task Group (B-10a)

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A joint standard developed by the JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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